

Barsky et al.

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IN THE SPECIFICATIONAmend paragraph {0024} as follows:

**[0024]** Sawing of a semiconductor wafer is accomplished after the wafer has been processed to form a large number of copies of a semiconductor device on the upper surface, such as the semiconductor device 1 pictorially illustrated (not-to-scale) in the die or chip 3 in Fig. 1. As pictorially represented in Fig. 2, those semiconductor devices 1, only one of which is numbered, are typically arranged in a regular grid-like pattern on the surface of the ~~wafer 5~~ wafer 2, spaced a short distance from one another in rows and columns. That arrangement enables a circular saw to be moved along a series of parallel lines, the saw lines, first in one direction 7, and then in an orthogonal direction 9 thereto to define the small separate square or rectangular shaped regions of wafer real estate, referred to as chips or die.